



(11) Publication number : **0 540 451 A3**

(12)

EUROPEAN PATENT APPLICATION

(21) Application number : **92480153.3**

(51) Int. Cl.⁵ : **H01L 21/48, H05K 3/46**

(22) Date of filing : **09.10.92**

(30) Priority : **29.10.91 US 784281**

(43) Date of publication of application :
05.05.93 Bulletin 93/18

(84) Designated Contracting States :
DE FR GB

(88) Date of deferred publication of search report :
08.12.93 Bulletin 93/49

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(54) **Structure and process for thin film interconnect.**

(57) This invention relates generally to a structure and process for thin film interconnect, and more particularly to a structure and process for a multilayer thin film interconnect structure (75) with improved dimensional stability and electrical performance. The invention further relates to a process of fabrication of the multilayer thin film structures (75). The individual thin film structure (50) is termed a compensator, and functions as both a ground/reference plane and as a stabilizing entity with regard to dimensional integrity. The compensator (50) is comprised primarily of a metal sheet (17) having a metallized via pattern (41) and high-temperature stable polymer (25) as an insulator.

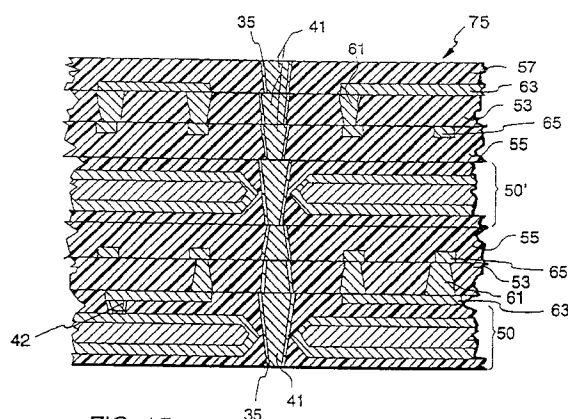


FIG. 15



European Patent
Office

EUROPEAN SEARCH REPORT

Application Number

EP 92 48 0153

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int. Cl.5)
A	US-A-4 963 697 (PETERSON ET AL.) * column 3, line 20 - line 34 * * column 3, line 50 - line 64 * * figures 2,3 * ---	1-5,8,9	H01L21/48 H05K3/46
A	IBM TECHNICAL DISCLOSURE BULLETIN. vol. 32, no. 3A, August 1989, NEW YORK US pages 122 - 124, XP49338 'Improved processes and materials for filling low dielectric power cores' ---		
A	US-A-2 961 746 (LYMAN) ---		
A	WO-A-9 014 751 (ROGERS CORPORATION) -----		
The present search report has been drawn up for all claims			TECHNICAL FIELDS SEARCHED (Int. Cl.5)
			H01L H05K
Place of search	Date of completion of the search	Examiner	
THE HAGUE	08 OCTOBER 1993	MES L. A.	
CATEGORY OF CITED DOCUMENTS			
X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document		T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons ----- & : member of the same patent family, corresponding document	

EPO FORM 1503 (03.82) (P0401)